

Electronic Acknowledgement Receipt

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Application Number:	10749096
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Title of Invention:	MULTI-LAYER INTEGRATED SEMICONDUCTOR STRUCTURE HAVING AN ELECTRICAL SHIELDING PORTION
First Named Inventor:	Rafael Reif
Customer Number:	22494
Filer:	Christopher S. Daly/Trish McHugh
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File Listing:

Document Number	Document Description	File Name	File Size(Bytes)	Multi Part	Pages
1		TO_PTO_DEFICIENCY_LE TTER.pdf	87436	yes	3

	Multipart Description		
	Doc Desc	Start	End
	Miscellaneous Incoming Letter	1	1
	Miscellaneous Incoming Letter	2	3
Warnings:			
Information:			
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